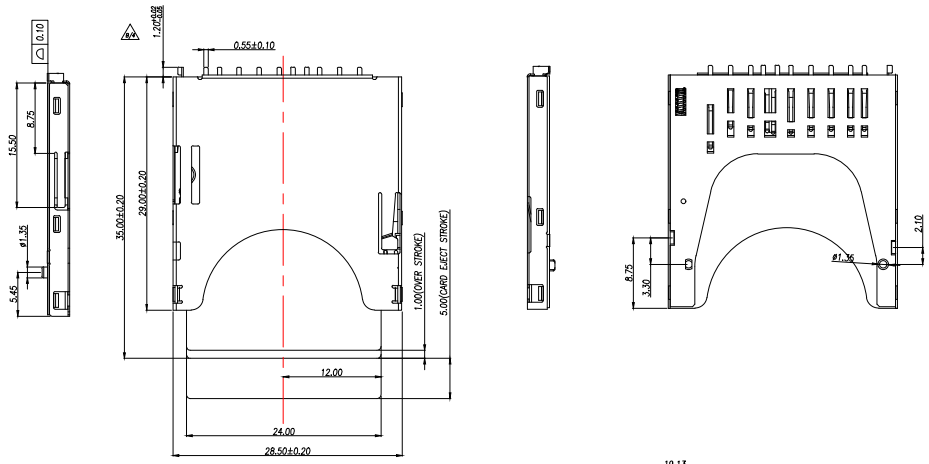
REV.	DESCRIPTION	ECN NO.	NAME	DATE

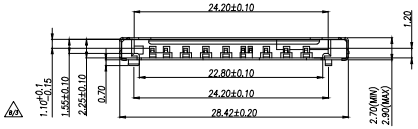


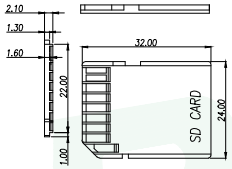
NOTES:

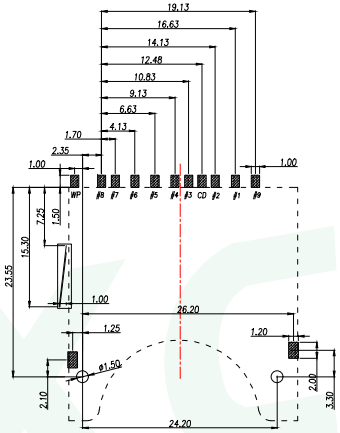
1.MATERIAL:
- HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0,COLOR:BLACK.
- CONTACT: COPPER ALLOYS.
- COVER: COPPER ALLOYS OR STEEL.

2.PLATING:
- UNDERPLATE: NICKEL.
- CONTACT AREA: GOLD OVER NICKEL.
- SOLDER AREA: TIN OVER NICKEL.

3.MULTIMEDIA CARD COMPATIBLE







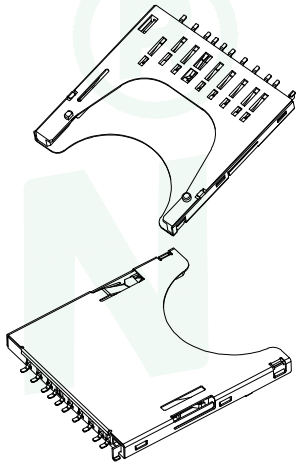
PAD AREA

KEEP OUT AREA

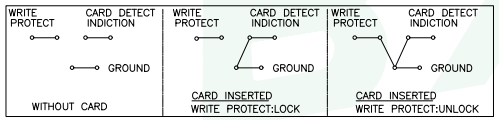
RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05

SD CARD PIN DEFINE			
Pin#	Name	Type	Description
1	CD/DAT3	I/O/PP	Card Detelct/ Date Line[Bit3]
2	CMD	PP	Command/Response
3	Vss1	S	Supply voltage ground
4	VDD	S	Supply voltage
5	CLK	I	Clock
6	Vss2	S	Supply voltage ground
7	DAT0	I/O/PP	Date Line [Bit0]
8	DAT1	I/O/PP	Date Line [Bit1]
9	DAT2	I/O/PP	Date Line [Bit2]
10	CD		CARD DETECT
11	WP		WRITE PROTECT



CIRCUIT:



GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD				BXCONN®
DIM. TOL. X X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 GENERAL ANGLE: ±3°	TITLE: SD CARD CONN PUSH SMT				
	DWG. NO.: SD-TD11P			DRAWN: MAX	
	PART NO.: SD-TD11P			CHECKED: ELLA	
	UNIT: mm	SCALE: none	SHEET: 1of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL